

ABSTRACT

A radiation sensitive resin composition which contains a specific amount of a fluorescent material and has high sensitivity, high resolution, excellent highly normalized film remaining characteristics, and capability to form a good pattern. In the case that the radiation sensitive resin composition comprises at least both a resin and a photosensitive material, such as an alkali-soluble novolak resin and a quinonediazide compound, the fluorescent material is used in an amount of 0.0001 to 1.0 parts by weight relative to 100 parts by weight of the photosensitive material. In the case that the radiation sensitive resin composition comprises at least both a resin and a photoacid generator, such as a positive-working or negative-working chemically amplified resist, the fluorescent material is used in an amount of 1.0 to 30.0 parts by weight relative to 100 parts by weight of the photoacid generator. The fluorescent material to be used is an organic fluorescent material such as a naphthalene, an anthracene, a phenanthrene, a pyrene, a perylene, a fluorene, a carbazole, a biphenyl, a p-terphenyl, a p-quaterphenyl, an indole, an acridine, a naphthacene, a rublene, a chrysene, or the like.